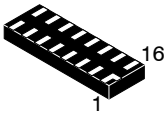
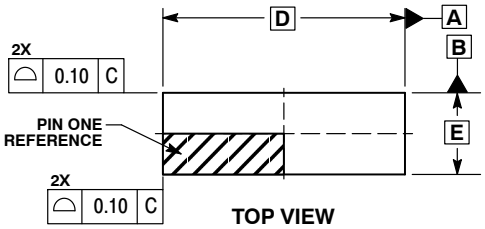


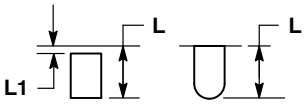
SCALE 4:1

XDFN16 4.0x1.35, 0.5P
CASE 711AZ
ISSUE O

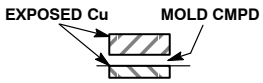
DATE 09 SEP 2014



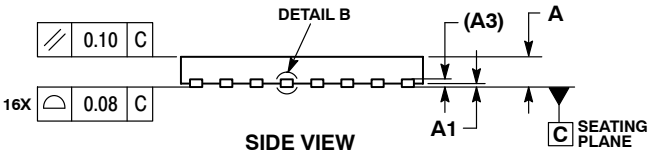
TOP VIEW



DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS



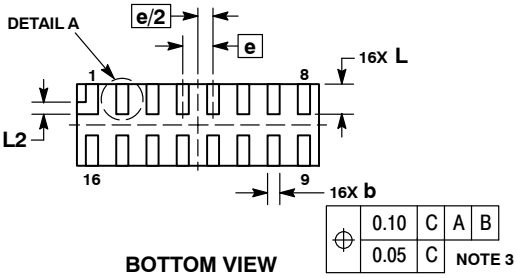
DETAIL B
ALTERNATE CONSTRUCTION



SIDE VIEW

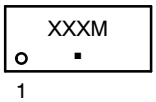
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

	MILLIMETERS	
DIM	MIN	MAX
A	0.40	0.50
A1	0.00	0.05
A3	0.15 REF	
b	0.15	0.25
D	4.00 BSC	
E	1.35 BSC	
e	0.50 BSC	
L	0.40	0.60
L1	---	0.15
L2	0.20 REF	



BOTTOM VIEW

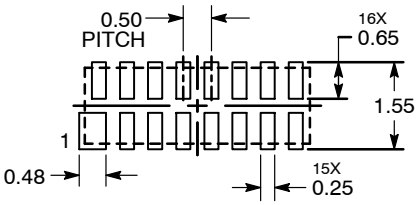
GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Month Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	XDFN16 4.0X1.35, 0.5P	PAGE 1 OF 1

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